Abstracts

Guest Editorial (Oct. 1997, Part I [T-MTT])

V.K. Tripathi and R. Sturdivant. "Guest Editorial (Oct. 1997, Part I [T-MTT])." 1997 Transactions on Microwave Theory and Techniques 45.10 (Oct. 1997, Part II [T-MTT] (Special Issue on Interconnects and Packaging)): 1817-1818.

With the advancements in RFIC, MMIC, and VLSI technologies, packaging of the resultant high-speed digital, RF and microwave, and millimeter-wave integrated circuits and systems in a cost-effective and high-performance manner has become a major challenge. The convergence of modern communication and computer technologies and the startling growth of corresponding high-frequency commercial electronics has brought new demands for increased performance with simultaneous decreases in cost and size on both integrated circuits and packaging and interconnect technologies.

❏ Return to main document.

Click on title for a complete paper.